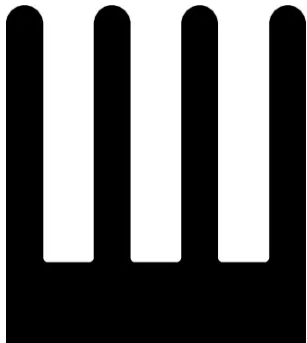


Data sheet Product ICK SMD K 19 MI



Heatsinks and active heatsinks for processors>Heatsinks for DIL-IC, PLCC and SMD

13,5 x 15,24 mm, for SMD components and others

Features

case type:	SMD
width:	13.5 mm
height:	15.24 mm
plate thickness:	3.5 mm
length:	19 mm
thermal resistance:	18 K/W
surface:	solderable surface

Technical Drawing

